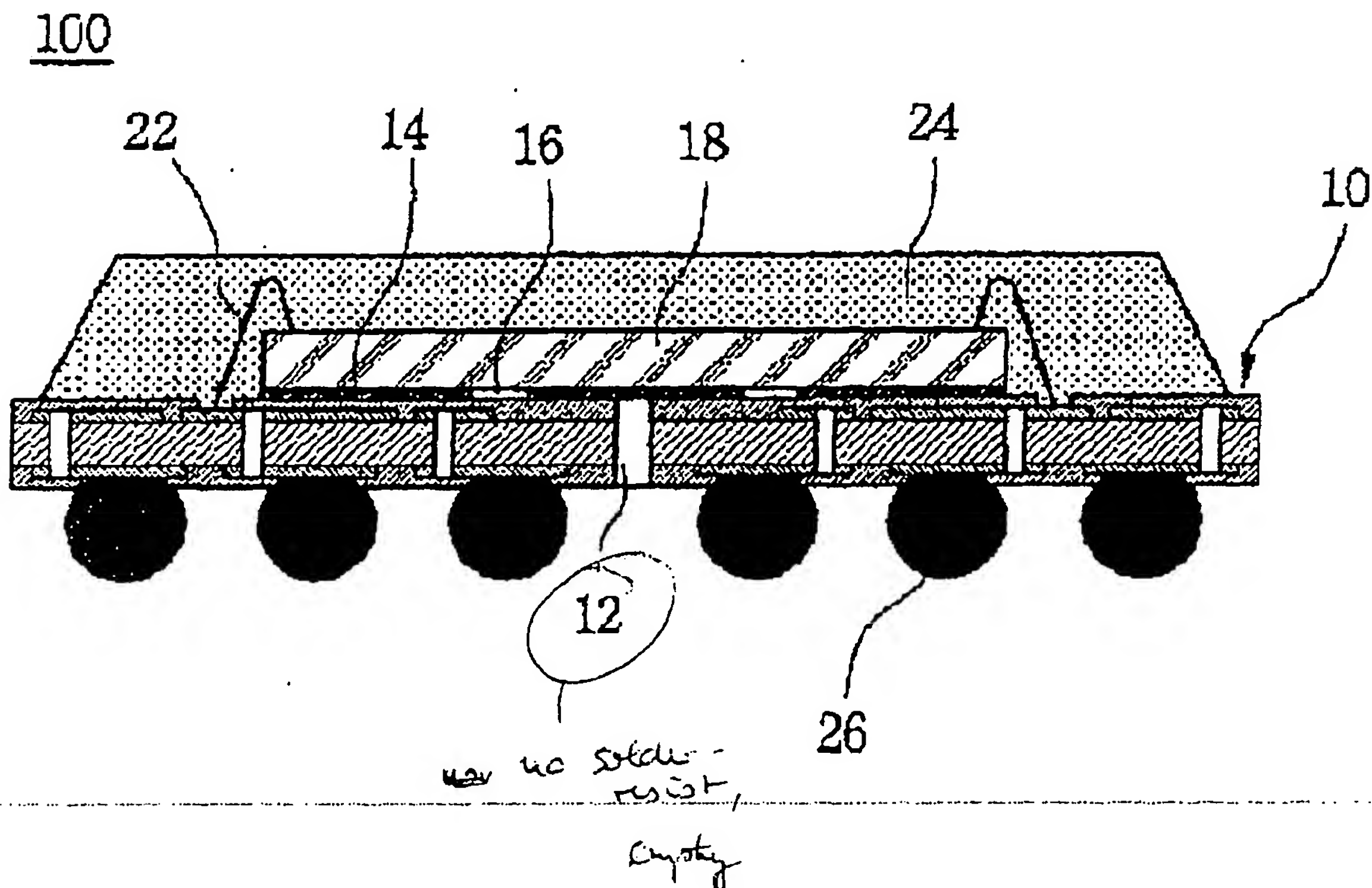


AN: PAT 2003-117955
 TI: Semiconductor package and manufacturing method thereof
 PN: KR2002064592-A
 PD: 09.08.2002
 AB: NOVELTY - A semiconductor package and a manufacturing method thereof are provided to effectively emit the remaining moisture in a package by connecting vent paths and a vent hole.
 DETAILED DESCRIPTION - A semiconductor package(100) comprises a semiconductor package manufacturing PCB(Printed Circuit Board) (10) formed with a vent hole(12) on a chip mount region, an adhesive part(14) deposited on the chip mount region of the PCB(10) except for the vent hole(12), a semiconductor chip(18) fixed on the adhesive part(14), wires(22) respectively connected between wire bonding regions of the PCB and bond pads of the semiconductor chip(18) and a molding resin(24) for enclosing on the upper portion of the resultant structure including the semiconductor chip(18) and the wires(22). At this time, the adhesive part(14) has a lattice-type vent paths(16).;
 PA: (AMKO-) AMKOR TECHNOLOGY KOREA INC;
 IN: HA S H; PARK Y G;
 FA: KR2002064592-A 09.08.2002;
 CO: KR;
 IC: H01L-023/12;
 MC: U11-D02; V04-T03;
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